

 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD	客户代码 Customer No.	1200	线图号 Drawing No.	HY-PX-1200-077 A		页码 Page 1 / 5
	产品名称 Product Type	STR21230-33 E3.0 E3.1		封装外型 PKG Type	FCLGA24L(2.4X2.2X0.60-P0.36)	

焊线图纸 Bonding Diagram

主要材料/BOM 清单信息 (Information of Material/BOM list):

样品验证，禁止量产！

材料			描述	供应商
1	基板	S23033JL3E	93. 81X93. 81X0. 21	客供
2	晶圆	WUM230SD1M	837.8*966.5(μm²)*200 (不包含bump高度) A芯	客供
3	助焊剂	TACFLUX 026S	/	钢泰

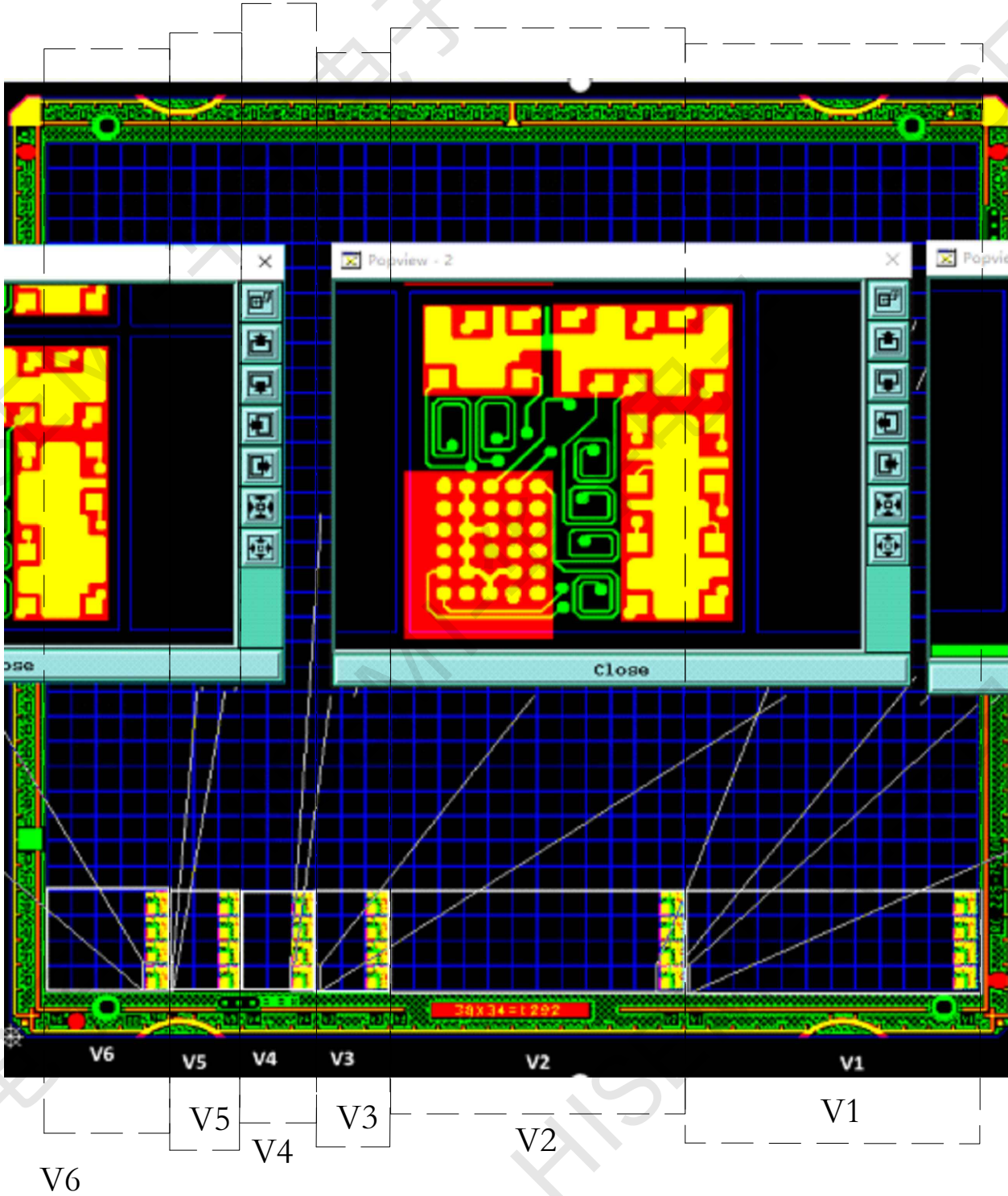
后切割道宽度	0.09mm
--------	--------

拟制 Prepared by		制图日期 Create Date	2025/12/26	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我司依据您回签后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

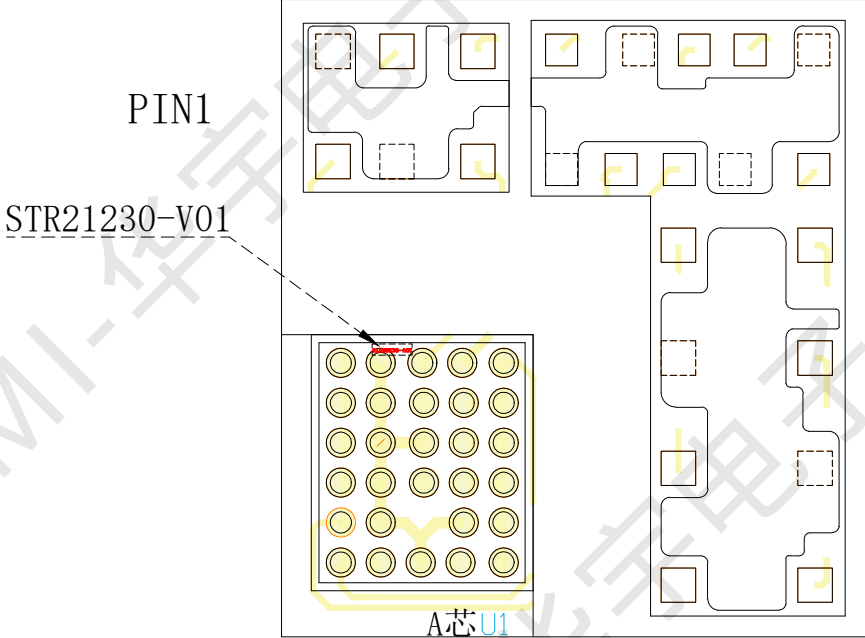
注意：贴装共用一条基板，基板贴V1-V6区域，根据工单指示封装区域，从右往左，V1第1列到第12列；V2第13列到第24列；V3第25列到第27列；V4第28列到第30列；V5第31列到第33列；V6第34列到第38列。

样品验证，禁止量产！

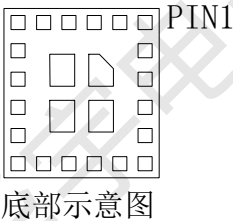


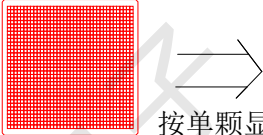
池州华宇电子科技有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.			1200		线图号 Drawing No.		HY-PX-1200-077 A			页码 Page 3 / 5	
	产品名称 Product Type						STR21230-33 E3.0 E3.1		封装外型 PKG Type		FCLGA24L(2.4X2.2X0.60-P0.36)	
助焊剂 Flux	/	/	/	/	/	/	塑封料型号(绿色环保) Compound Type (Green)			基板编码 Substrate No.		
TACFlux026S	/	/	/	/	/	/	首选(Preferred): / 备选(Optional):			S23033JL3E		
客户图号 Customer drawing NO.												

样品验证，禁止量产！



注意：
1.此图纸只做FC倒装贴U1这颗die,U1按照MAP取die;



框架传送方向（装片）： L/F Direction (D/A)：	实物图： Chip photo：	特殊说明 Special Instructions：
 按单颗显示方向进料		

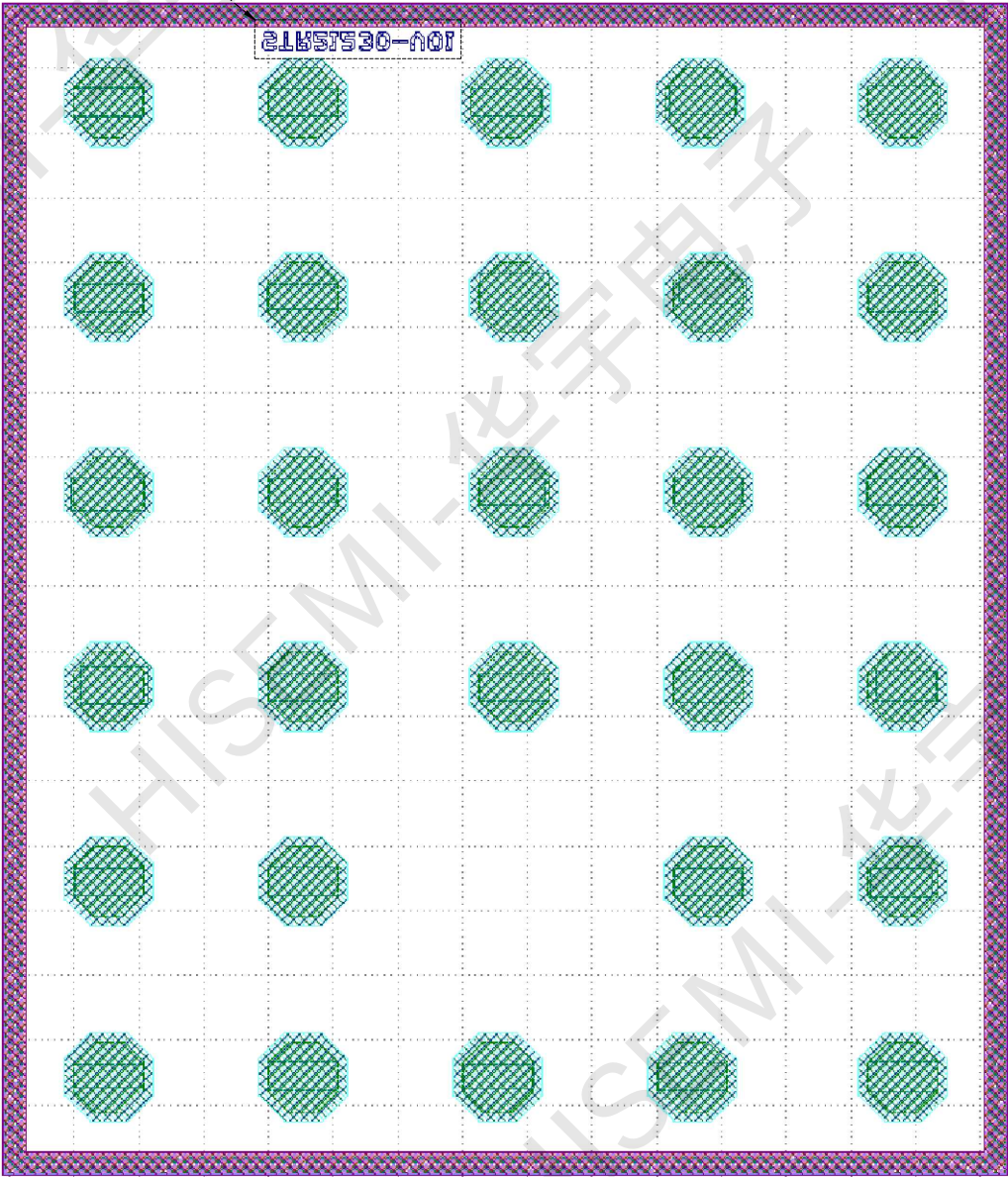
序号	芯片名称	Die ID	芯片尺寸 (with scribe line)	晶圆尺寸 (Wafer size)	划片道宽度	圆片工艺	芯片厚度 UM	来料方式	Wafer material*	Bump type*	Bump composition*	Min bump pitch (space + bump size)* UM	Min bump height* UM	Min bump diameter* UM
A 芯U1	WUM230SD1M	STR21230-V01	837.8*966.5(μm²) 32.98*38.05mil²	8寸	62um	NA	200um (不包含bump高度)	晶圆wafer	SOI	Copper Pillar Bump	35cu+3NI+30Sn	150	68	80
拟制 Prepared by		制图日期 Create Date			2025/12/26			生效日期 Effective Date		客户确认签字/盖章: Customer Signature				
研发审核 R&d check		产品工程审核 Product engineering check			批准 Approved by									

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

U1 ball map图 (TOP view)

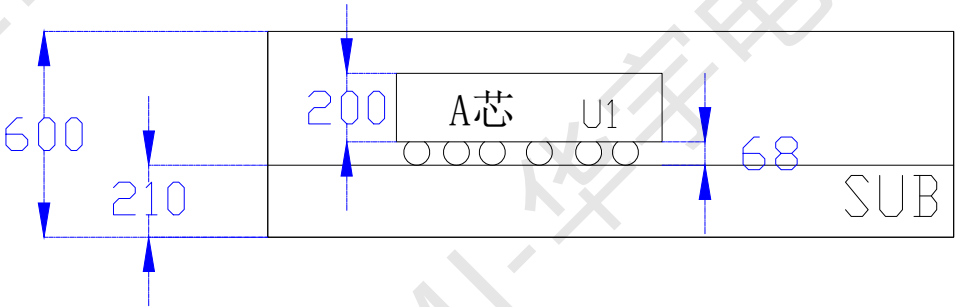
样品验证，禁止量产！

按目标区域取DIE:
ID: STR21230-V01



 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.	1200	线图号 Drawing No.	HY-PX-1200-077 A		页码 Page 5 / 5
	产品名称 Product Type	STR21230-33 E3.0 E3.1		封装外型 PKG Type	FCLGA24L(2.4X2.2X0.60-P0.36)	

样品验证，禁止量产！



拟制 Prepared by		制图日期 Create Date	2025/12/26	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you